Final Product/Process Change Notification

Document #:FPCN25905XB
Issue Date:05 Aug 2024

Title of Change:	Assembly Material Mold Compound Change for Sumitomo G600 to replace Kyocera KE-G3000D-4TV due to mold compound supply discontinuance for TSSOP 48 / 56 devices.
Proposed First Ship date:	12 Nov 2024 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Rob.Fazonela@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or Chielo.Basa@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Product traceability will be maintained by date code
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
None	ATEC - Automated Technology, Philippines

Description and Purpose:

This Final Product Change Notification (FPCN) is to notify customers that onsemi has qualified Sumitomo G600 mold compound as a replacement for existing Kyocera KE-G3000D-4TV mold compound for the devices listed in this notification due to supply discontinuance.

	From	**To**
Mold Compound	Kyocera KE-G3000D-4TV	Sumitomo G600

Reliability Data Summary:

QV DEVICE NAME: 74LCX16646MTDX
RMS: O92908
PACKAGE: TSSOP 56

Test	Specification	Condition	Interval	Results
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/240
Preconditioning	J-STD-020 JESD-A113	MSL 2 @ 260°C, Pre TC, uHAST for surface mount pkgs only		0/480
Temperature Cycling	JESD22-A104	Ta= -65°C to + 150°C	500 cyc	0/240
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
Solderability	JSTD002	Ta = 245°C, 5 sec		0/ 45
Physical Dimensions	JESD22-B100 and JESD22-B108	Per Case Outline		0/30

QV DEVICE NAME: 74LCX16245MTD
RMS: O92921
PACKAGE: TSSOP 48

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/240
Preconditioning	J-STD-020 JESD-A113	MSL 2 @ 260 °C, Pre TC, uHAST, HAST for surface mount pkgs only		0/240
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96hrs	0/240

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
74VCX16374MTDX	74LCX16646MTDX / 74LCX16245MTDX
74VCX16373MTDX	74LCX16646MTDX / 74LCX16245MTDX

74VCX16373MTD	74LCX16646MTDX / 74LCX16245MTDX
74VCX16244MTDX	74LCX16646MTDX / 74LCX16245MTDX
74VCX162373MTDX	74LCX16646MTDX / 74LCX16245MTDX
74VCX162244MTDX	74LCX16646MTDX / 74LCX16245MTDX
74ALVC16244MTDX	74LCX16646MTDX / 74LCX16245MTDX
74ALVC162244TX	74LCX16646MTDX / 74LCX16245MTDX
74VCX164245MTDX	74LCX16646MTDX / 74LCX16245MTDX